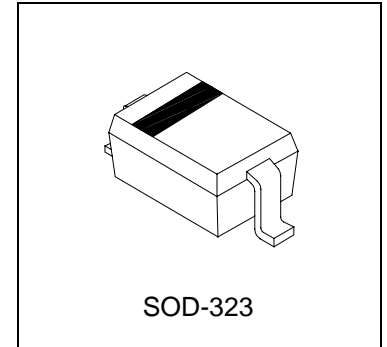




HMSZ5223B
thru
HMSZ5257B ZENER DIODES



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Total Device Dissipation FR-5 Board $T_A=25^{\circ}\text{C}$, Derate above 25°C	P_D	225 1.8	mW mW/ $^{\circ}\text{C}$
Total Device Dissipation Alumina Substrate** $T_A=25^{\circ}\text{C}$, Derate above 25°C	P_D	300 2.4	mW mW/ $^{\circ}\text{C}$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	417	$^{\circ}\text{C/W}$
Junction and Storage Temperature	T_J, T_{stg}	-55 to +150	$^{\circ}\text{C}$

*FR-5 - 1.0x0.75x0.062 in. **Alumina - 0.4x0.3x0.024 in. 99.5% alumina.

Electrical Characteristic ($V_F=0.9\text{V}(\text{Max.})$ @ $I_F=10\text{mA}$ for all types.)

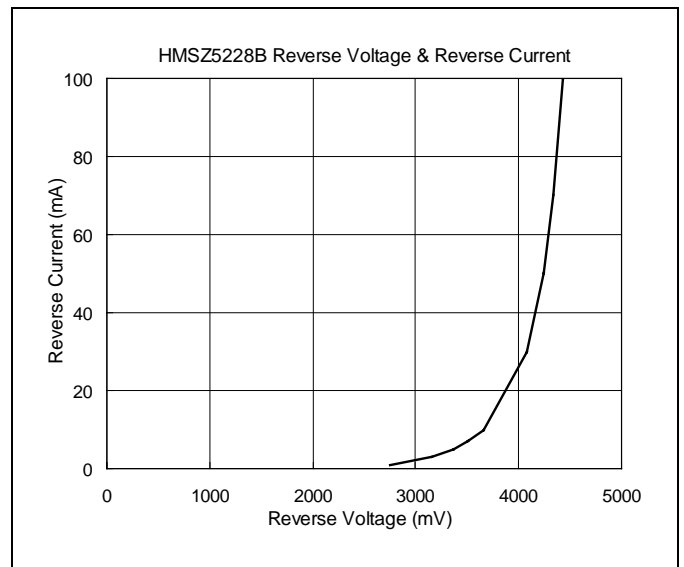
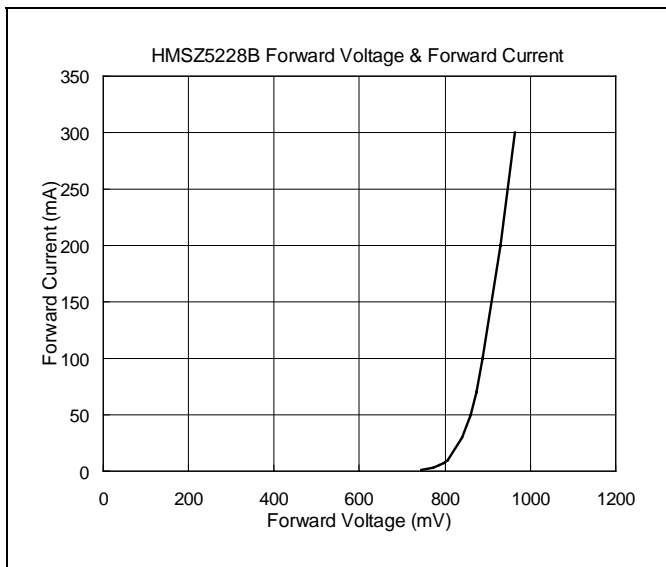
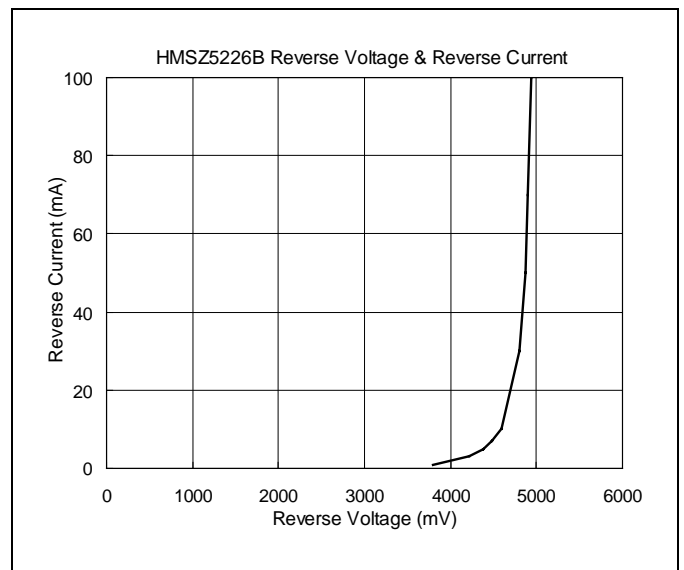
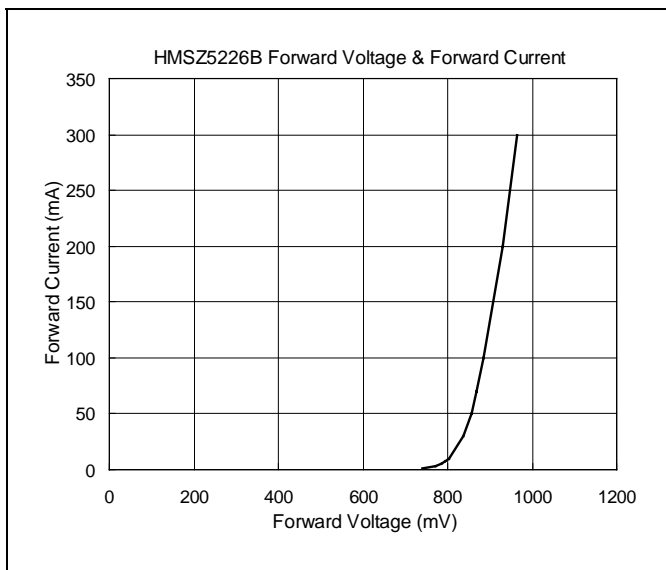
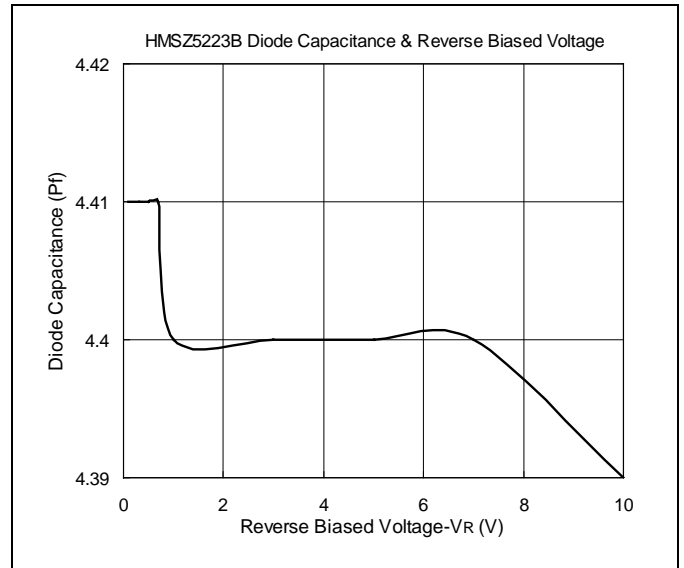
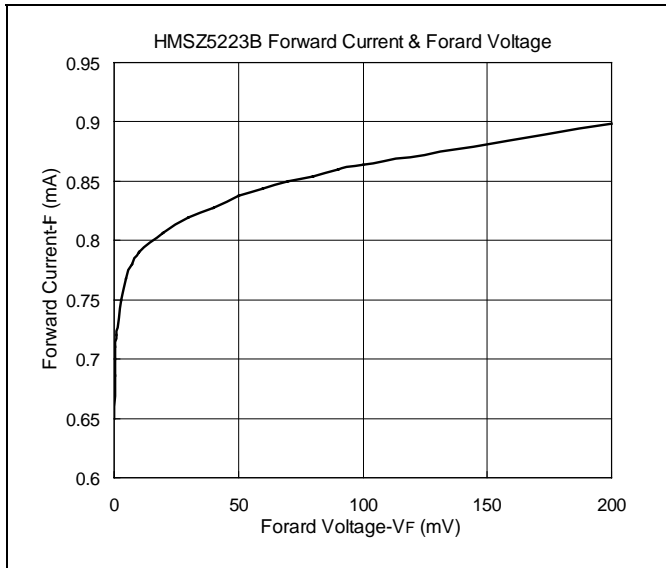
Device	Marking Code	Test Current $I_{ZT}(\text{mA})$	Zener Voltage $V_Z(\text{V})$	Z_{ZK} $I_Z=0.25\text{mA}$ $\Omega(\text{Max.})$	Z_{ZT} $I_Z=I_{ZT}$ $\Omega(\text{Max.})$	Max. Reverse Current	
						$I_R(\mu\text{A})$	@ $V_R(\text{V})$
HMSZ5223B	23	20	2.7 $\pm 5\%$	1300	30	75	1.0
HMSZ5226B	26	20	3.3 $\pm 5\%$	1600	28	25	1.0
HMSZ5227B	27	20	3.6 $\pm 5\%$	1700	24	15	1.0
HMSZ5228B	28	20	3.9 $\pm 5\%$	1900	23	10	1.0
HMSZ5229B	29	20	4.3 $\pm 5\%$	2000	22	5.0	1.0
HMSZ5230B	30	20	4.7 $\pm 5\%$	1900	19	5.0	2.0
HMSZ5231B	31	20	5.1 $\pm 5\%$	1600	17	5.0	2.0
HMSZ5232B	32	20	5.6 $\pm 5\%$	1600	11	5.0	3.0
HMSZ5233B	33	20	6.0 $\pm 5\%$	1600	7.0	5.0	3.5
HMSZ5234B	34	20	6.2 $\pm 5\%$	1000	7.0	5.0	4.0
HMSZ5235B	25	20	6.8 $\pm 5\%$	750	5.0	3.0	5.0
HMSZ5236B	36	20	7.5 $\pm 5\%$	500	6.0	3.0	6.0
HMSZ5237B	37	20	8.2 $\pm 5\%$	500	8.0	3.0	6.5
HMSZ5238B	38	20	8.7 $\pm 5\%$	600	8.0	3.0	6.5
HMSZ5239B	39	20	9.1 $\pm 5\%$	600	10	3.0	7.0
HMSZ5240B	40	20	10 $\pm 5\%$	600	17	3.0	8.0
HMSZ5241B	41	20	11 $\pm 5\%$	600	22	2.0	8.4
HMSZ5242B	42	20	12 $\pm 5\%$	600	30	1.0	9.1
HMSZ5243B	43	9.5	13 $\pm 5\%$	600	13	0.5	9.9

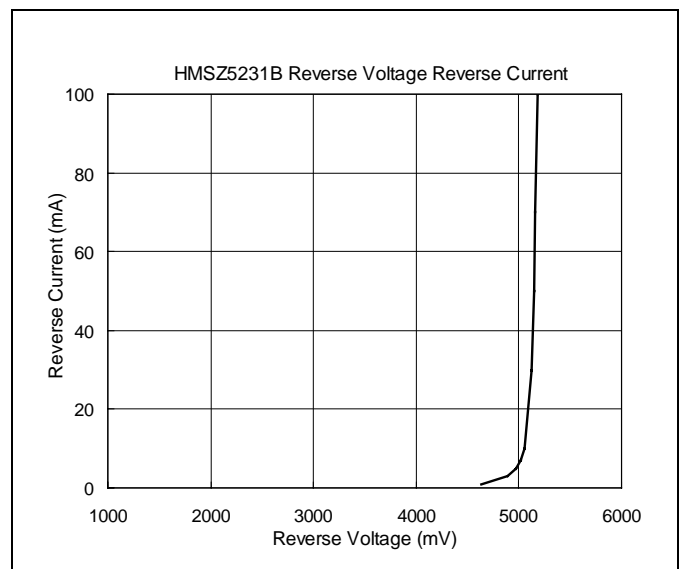
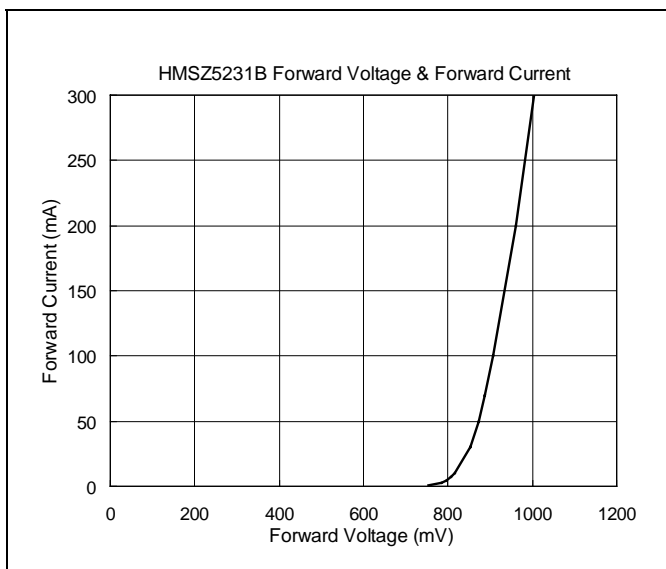
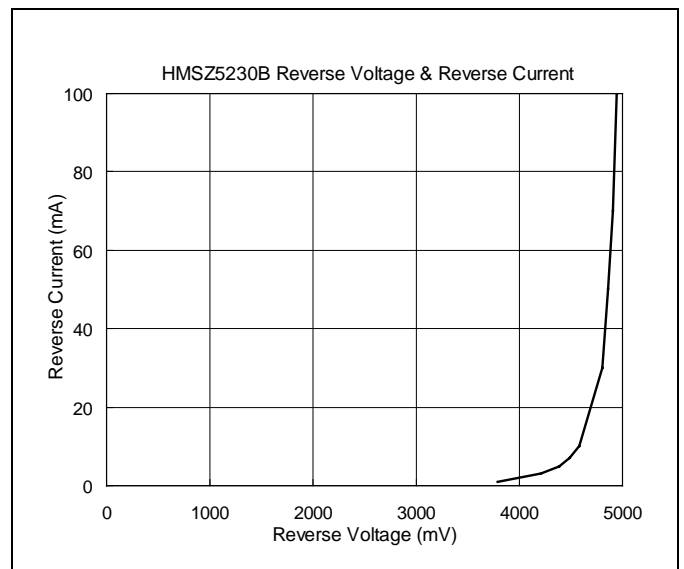
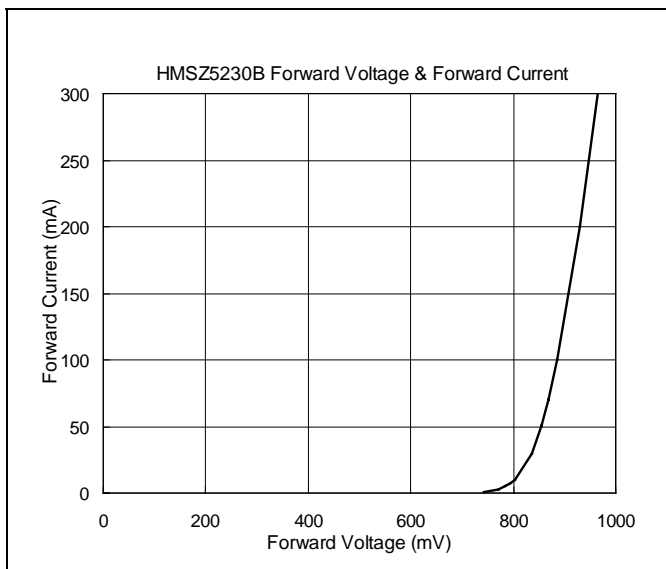
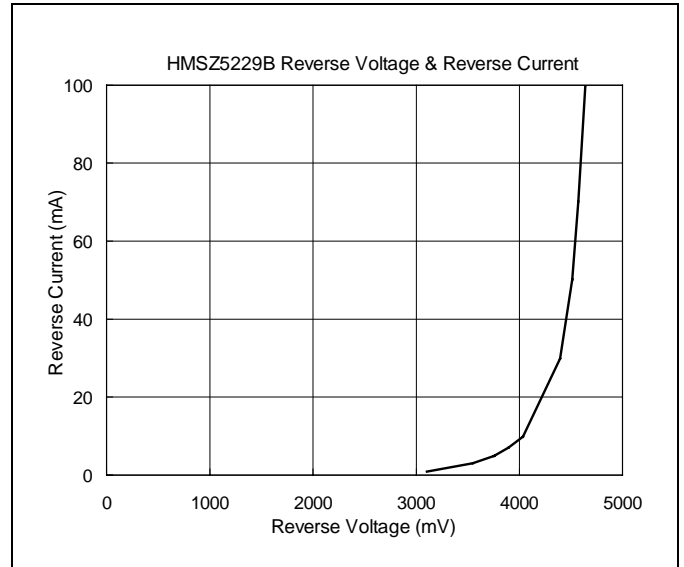
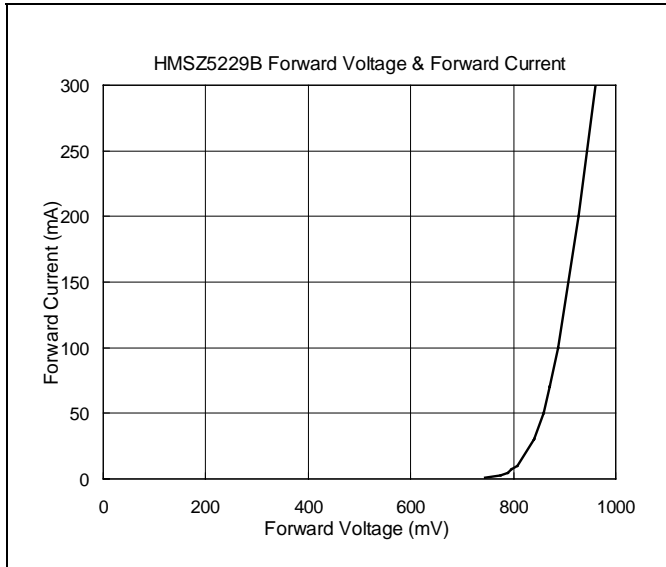


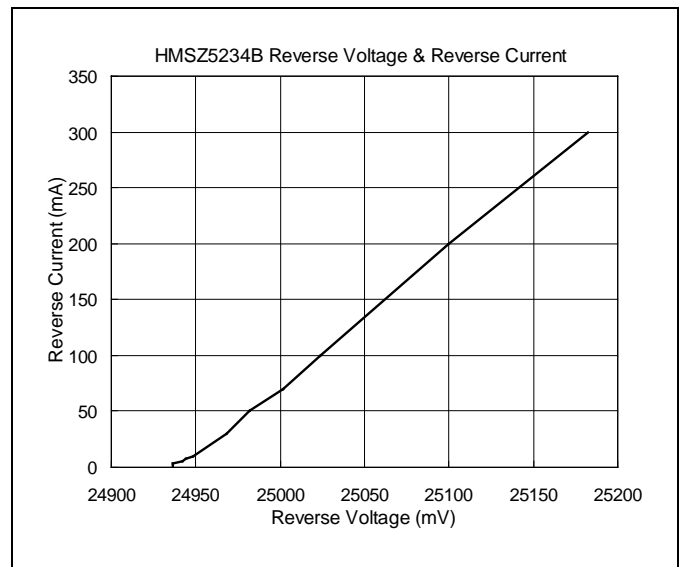
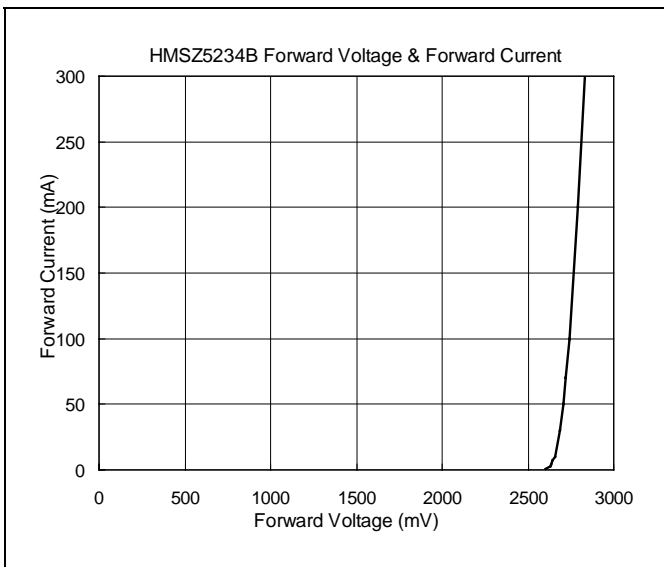
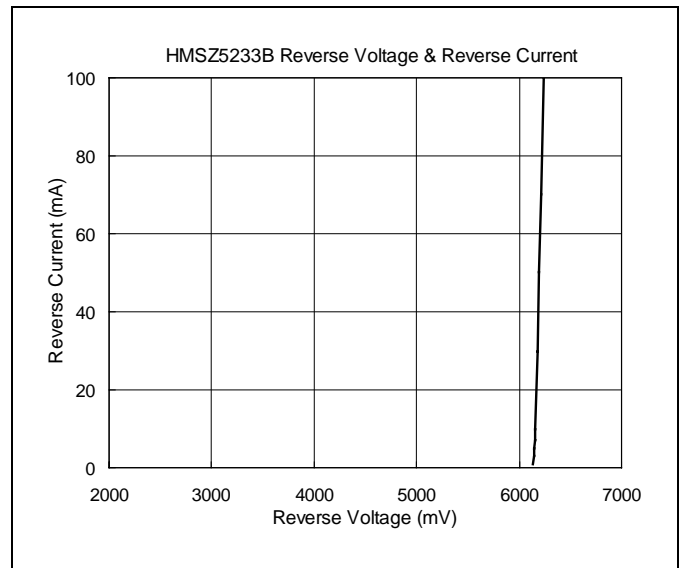
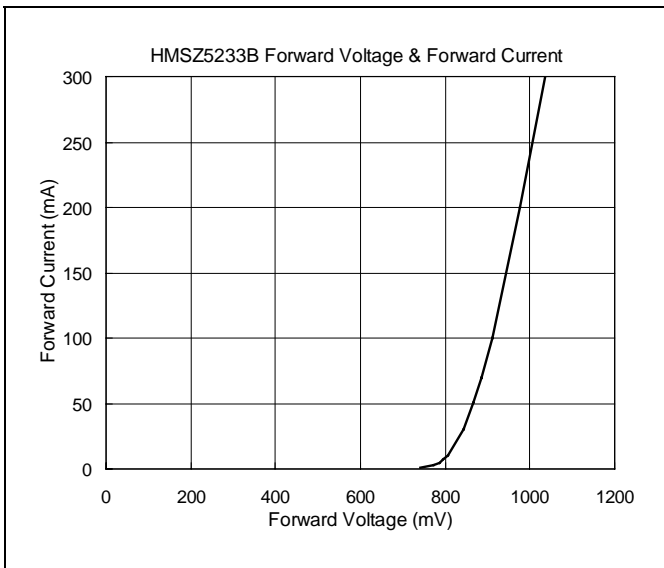
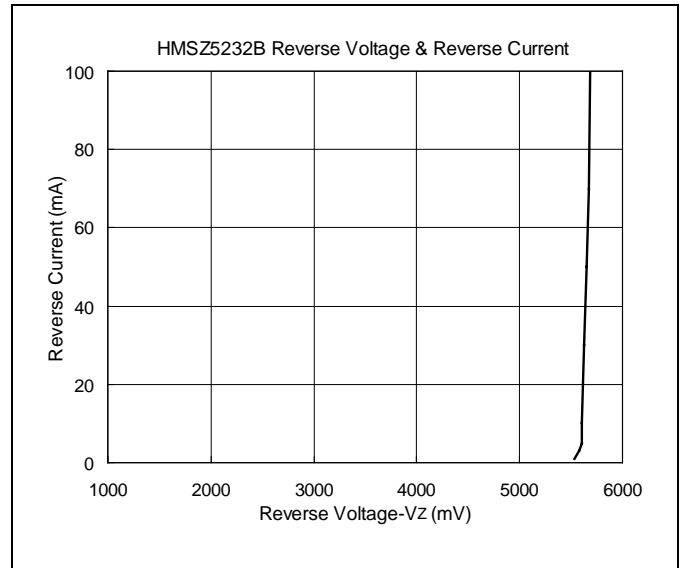
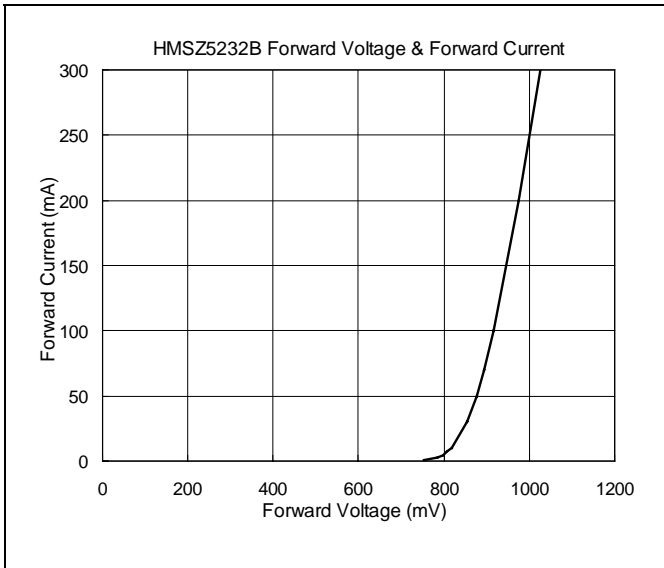
Device	Marking Code	Test Current I_{ZT} (mA)	Zener Voltage V_Z (V)	Z_{ZK} $I_Z=0.25mA$ Ω (Max.)	Z_{ZT} $I_Z=I_{ZT}$ Ω (Max.)	Max. Reverse Current	
						I_R (μ A)	@ V_R (V)
HMSZ5244B	44	9.0	14 \pm 5%	600	15	0.1	10
HMSZ5245B	45	8.5	15 \pm 5%	600	16	0.1	11
HMSZ5246B	46	7.8	16 \pm 5%	600	17	0.1	12
HMSZ5247B	47	7.4	17 \pm 5%	600	19	0.1	13
HMSZ5248B	48	7.0	18 \pm 5%	600	21	0.1	14
HMSZ5249B	49	6.6	19 \pm 5%	600	23	0.1	14
HMSZ5250B	50	6.2	20 \pm 5%	600	25	0.1	15
HMSZ5251B	51	5.6	22 \pm 5%	600	29	0.1	17
HMSZ5252B	52	5.2	24 \pm 5%	600	33	0.1	18
HMSZ5253B	53	5.0	25 \pm 5%	600	35	0.1	19
HMSZ5254B	54	4.6	27 \pm 5%	600	41	0.1	21
HMSZ5255B	55	4.5	28 \pm 5%	600	44	0.1	21
HMSZ5256B	56	4.2	30 \pm 5%	600	49	0.1	23
HMSZ5257B	57	3.8	33 \pm 5%	700	58	0.1	25

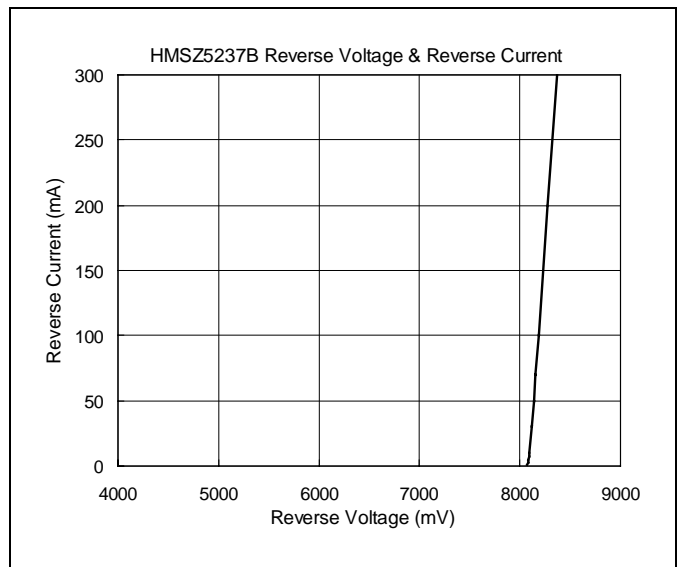
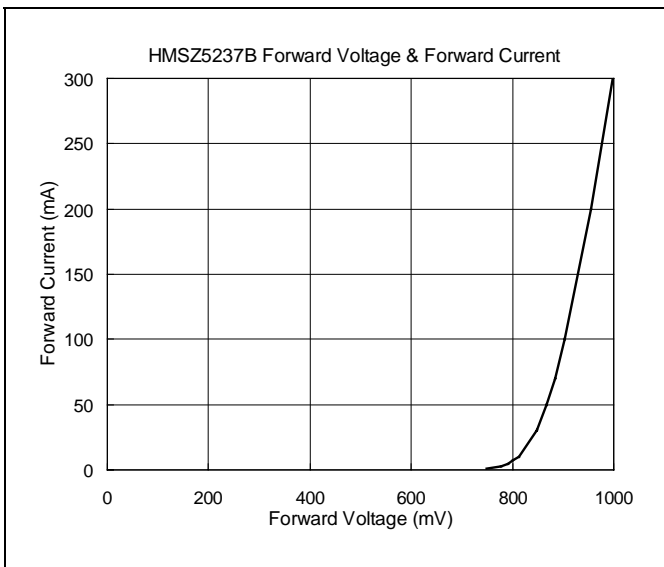
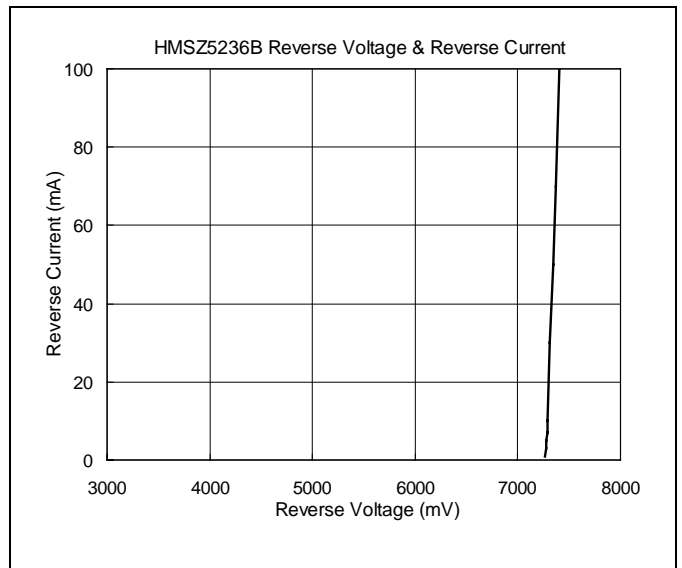
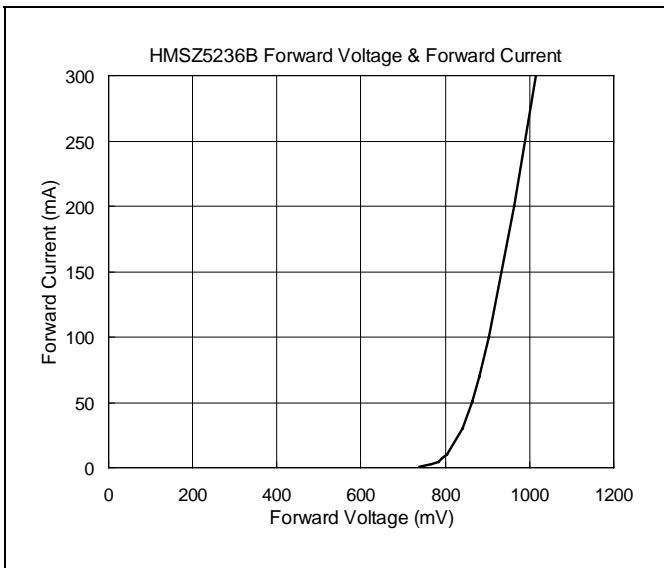
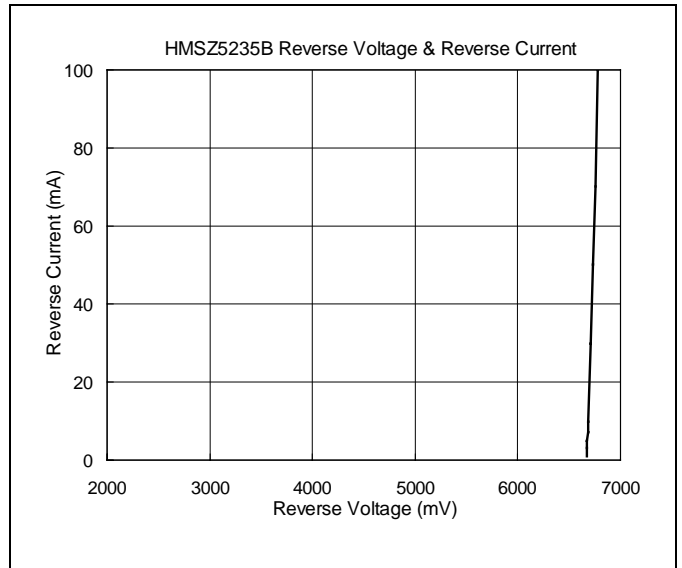
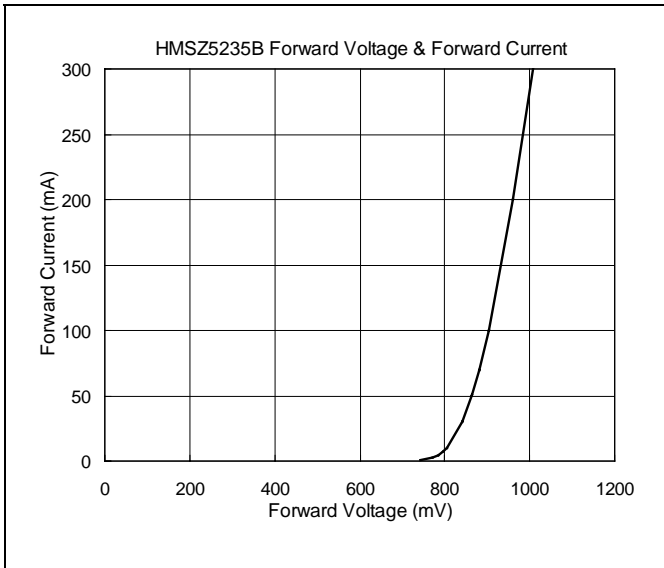


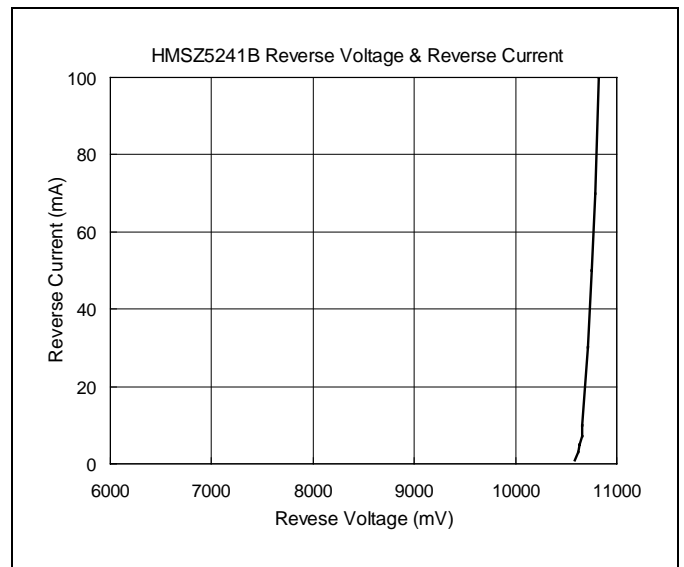
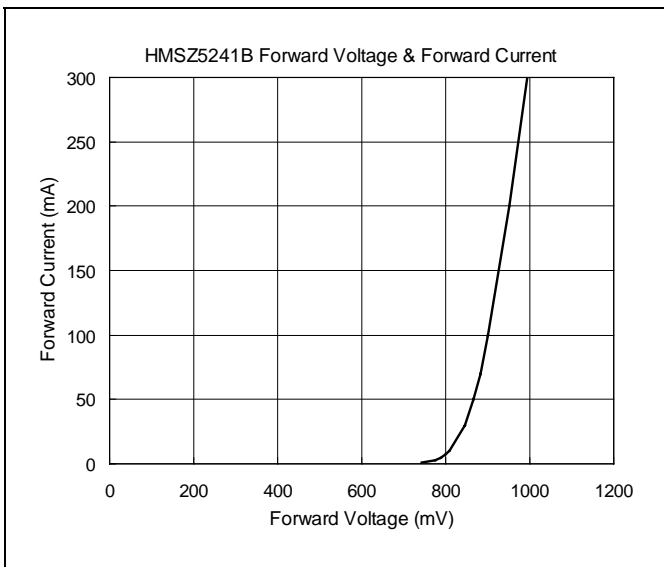
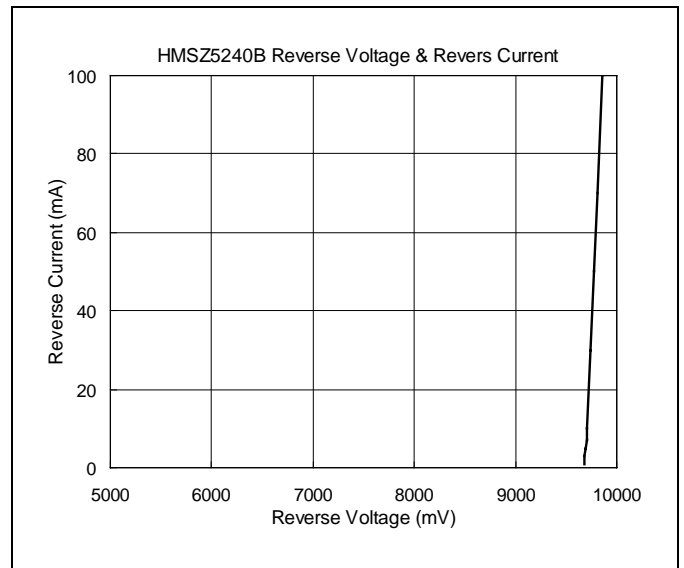
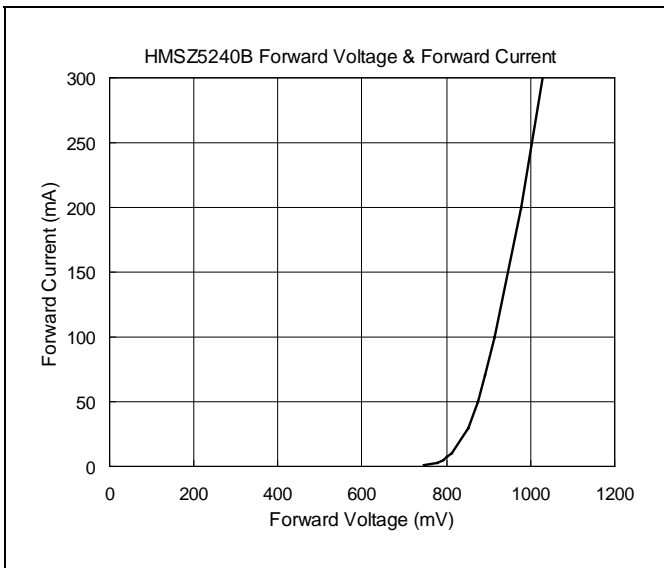
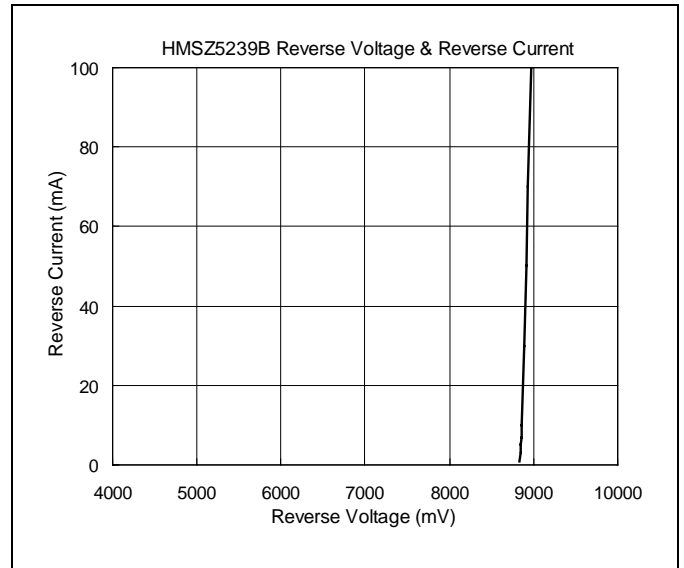
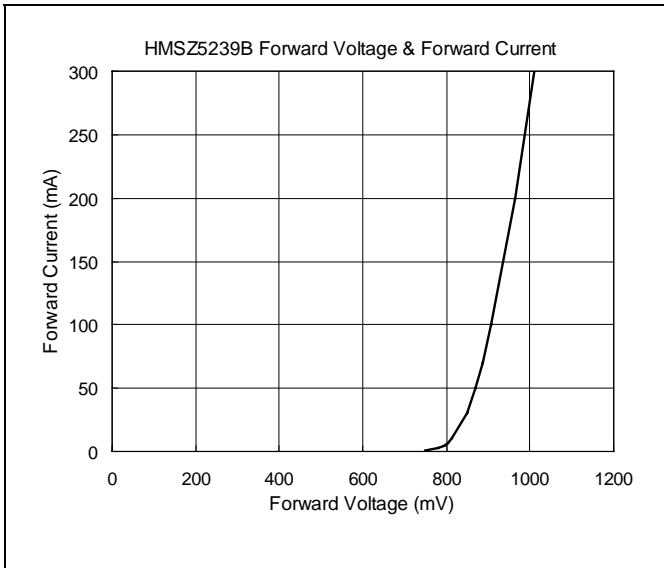
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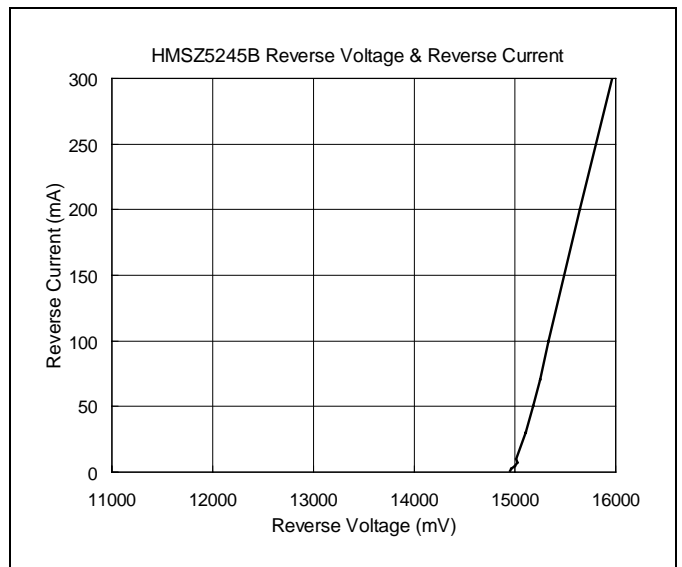
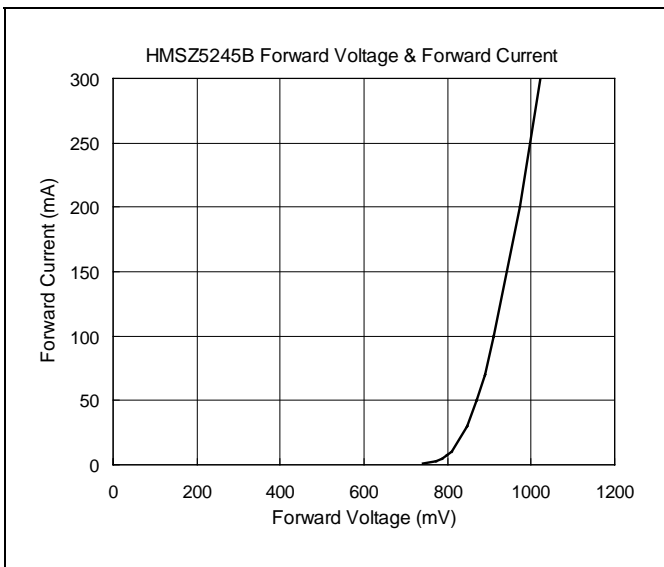
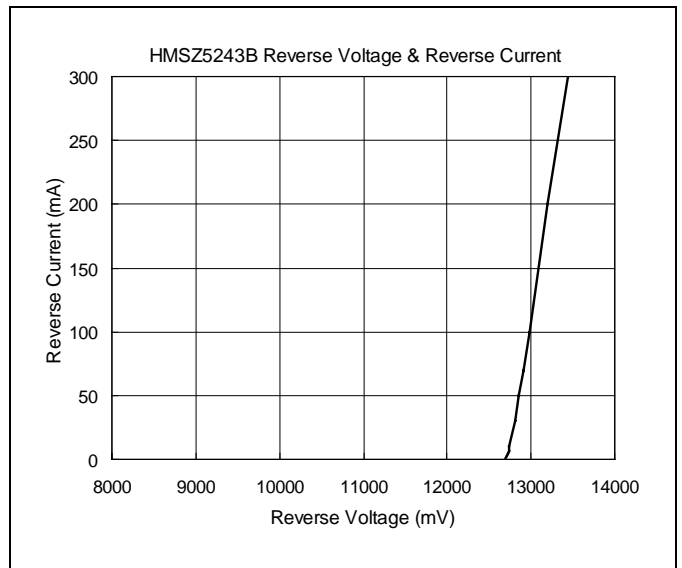
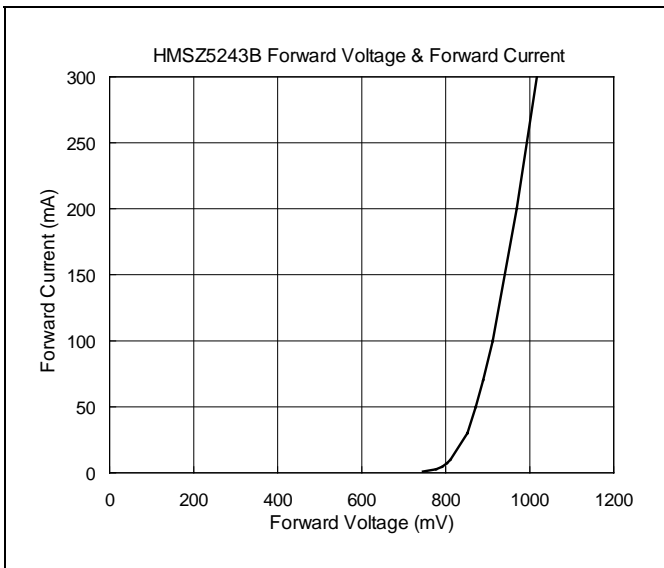
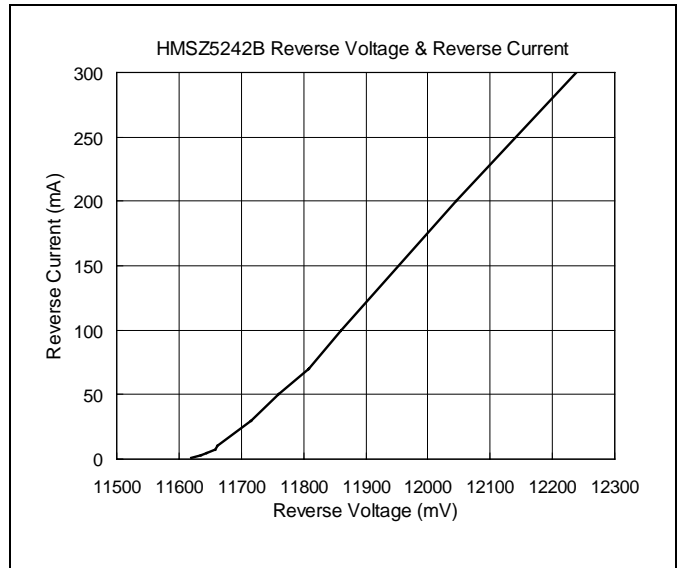
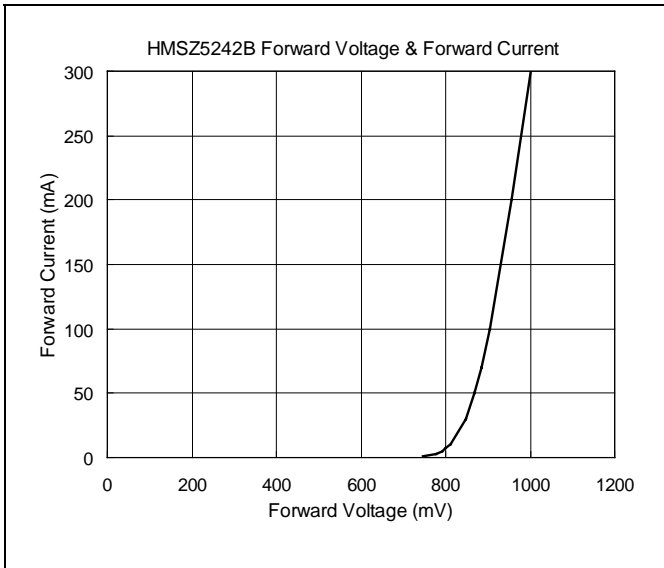


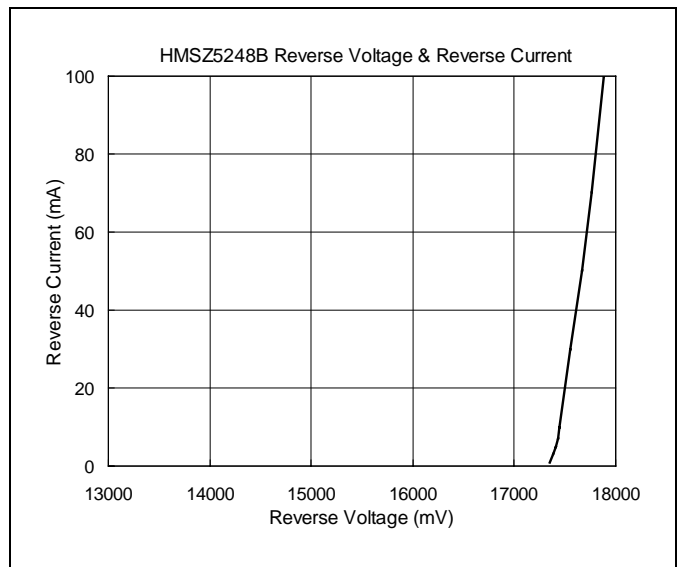
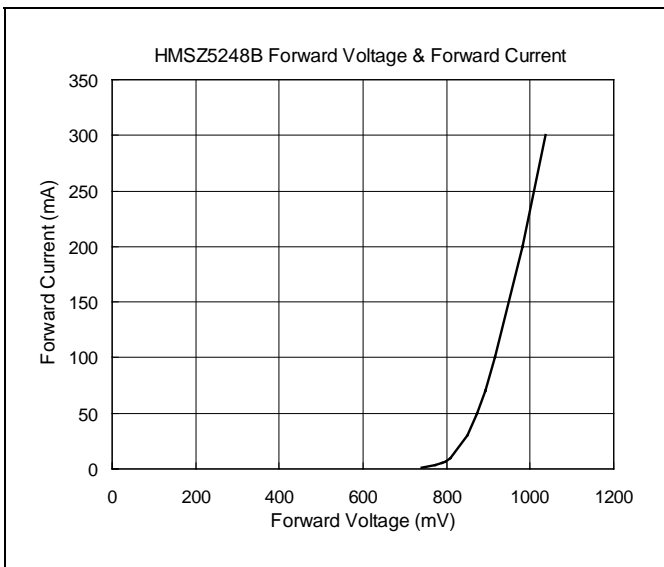
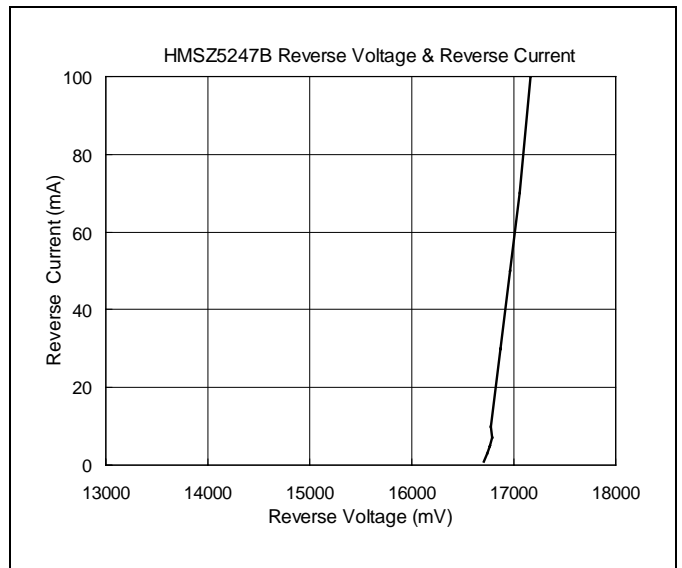
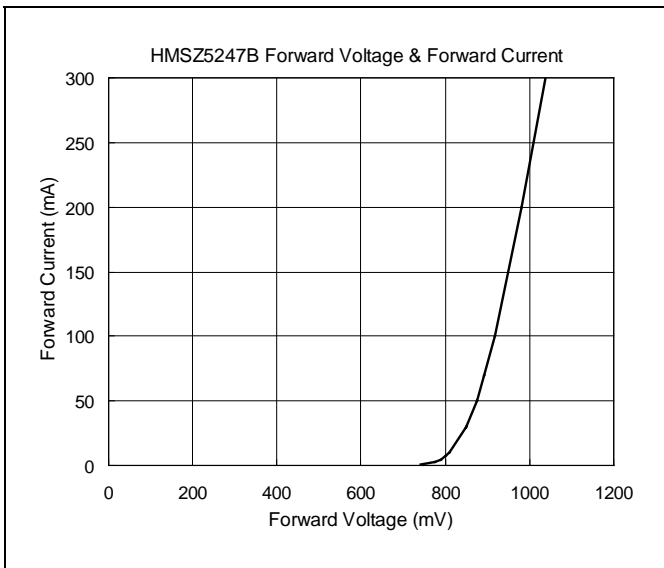
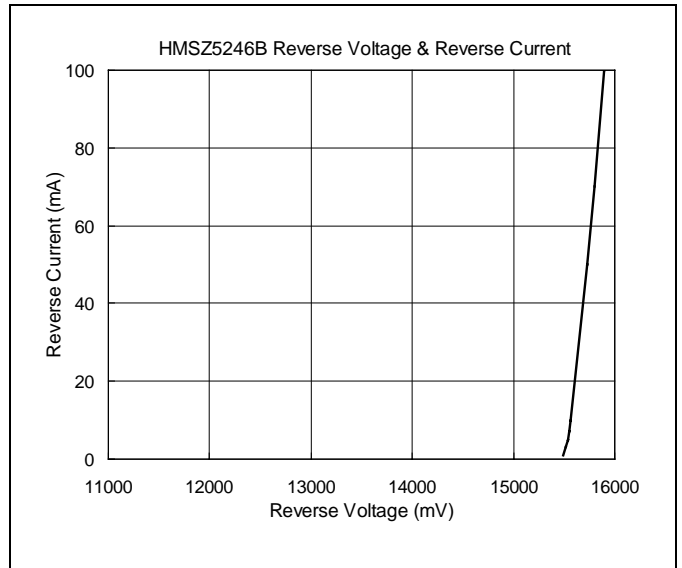
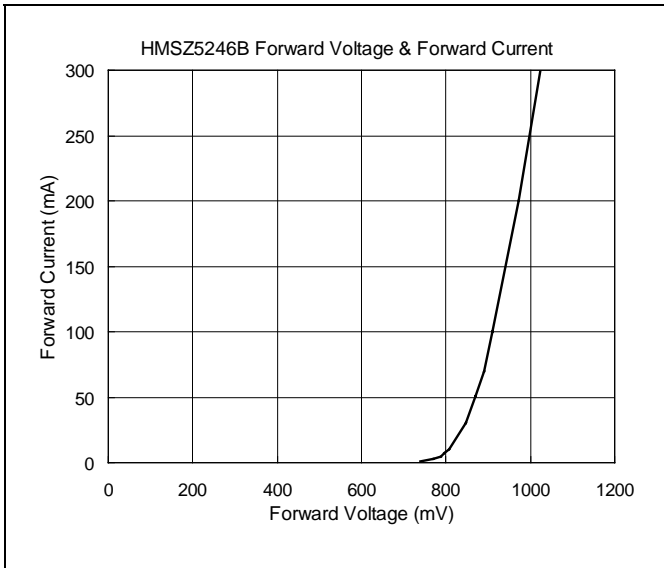


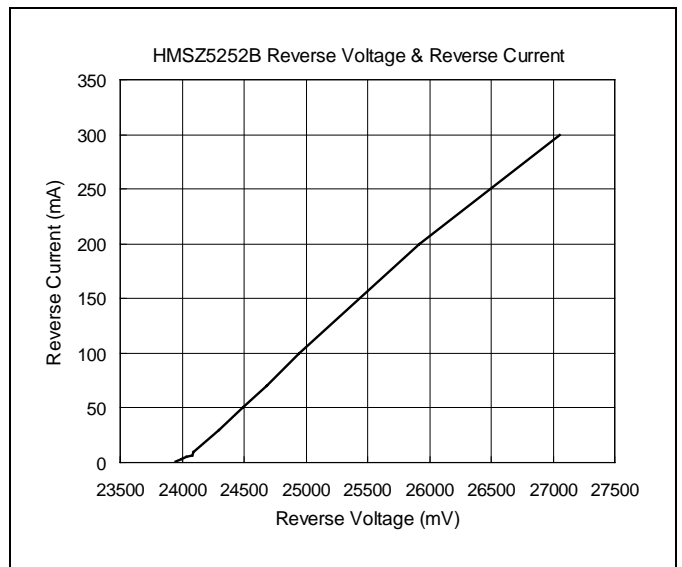
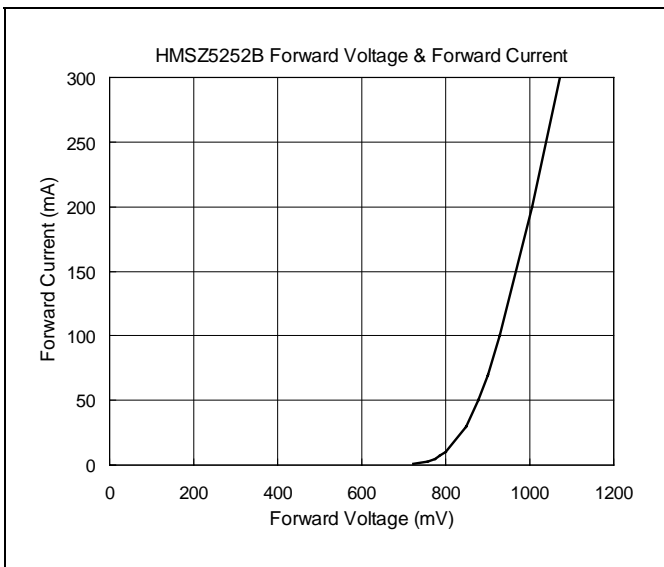
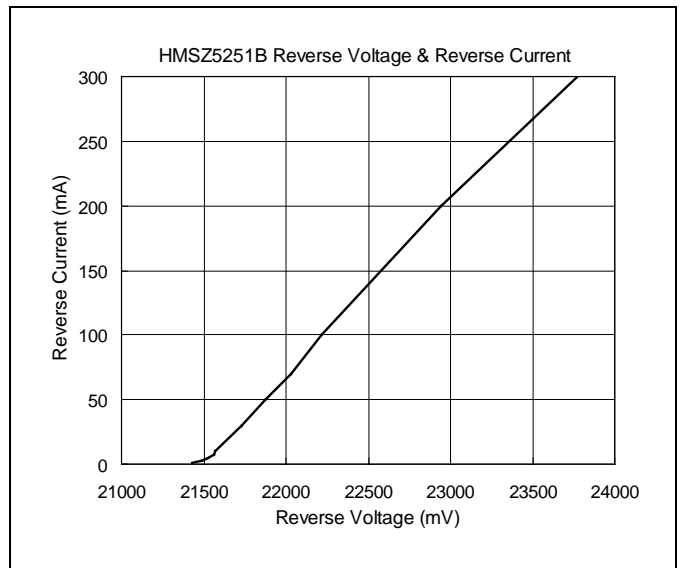
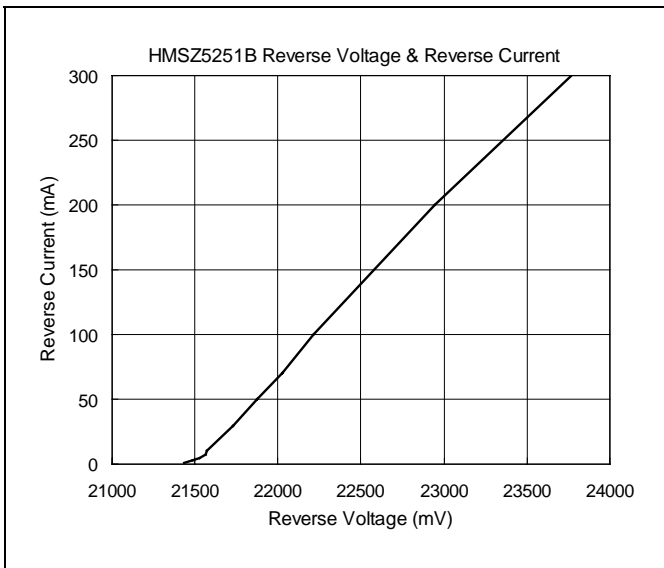
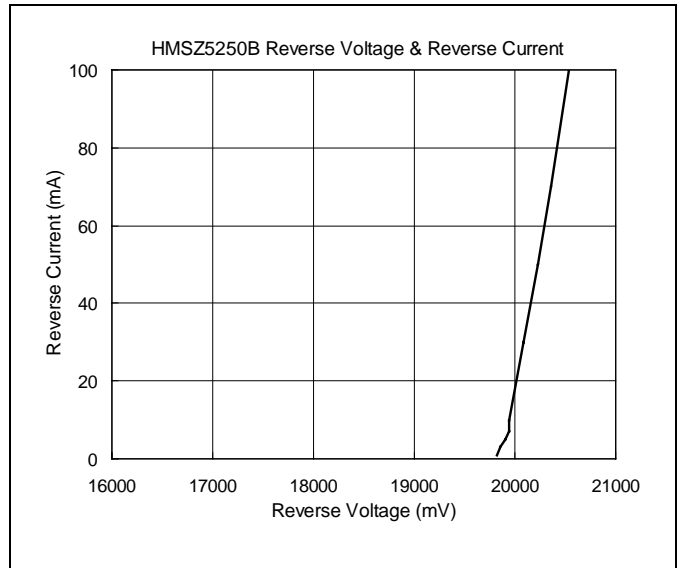
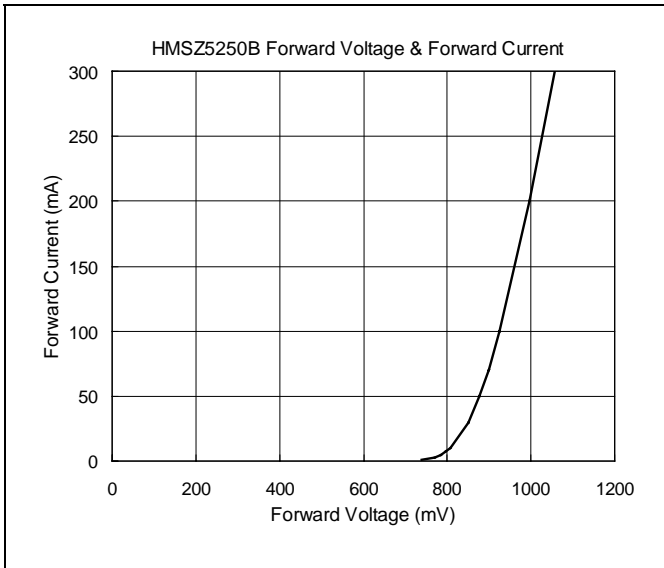


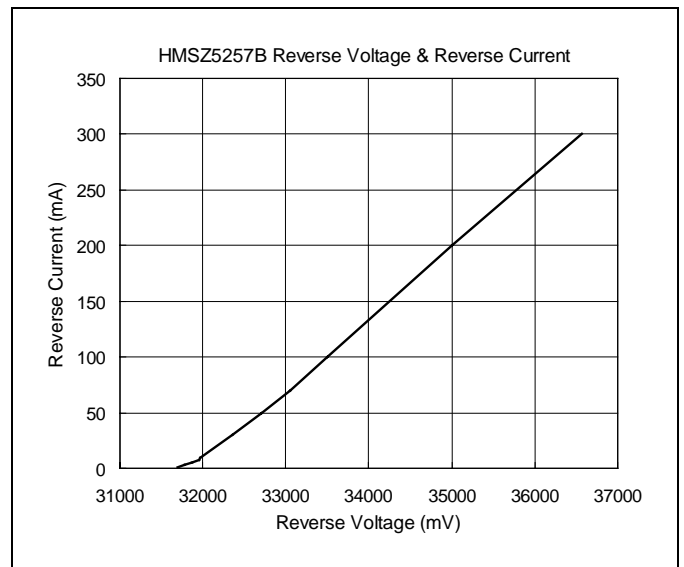
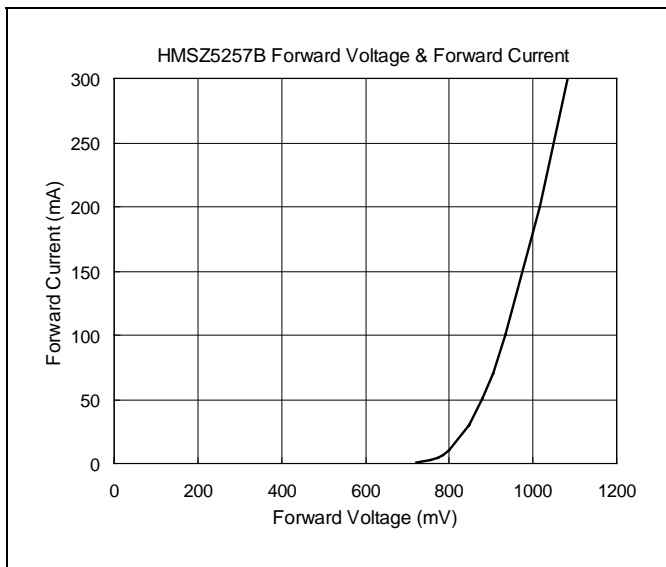
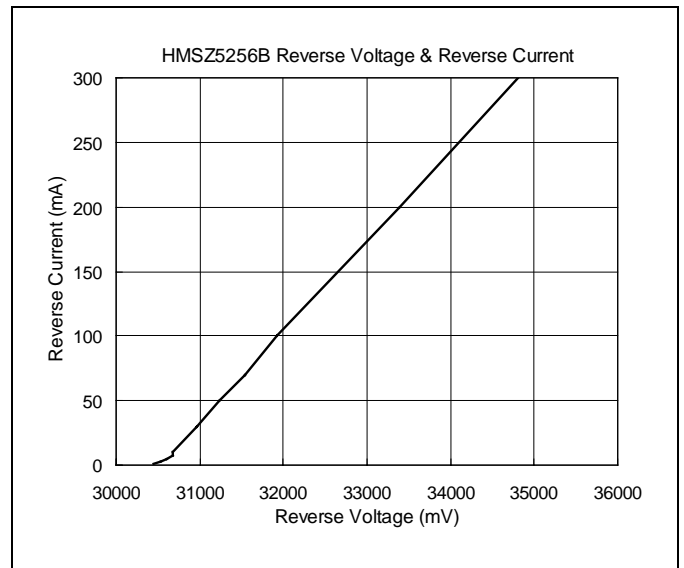
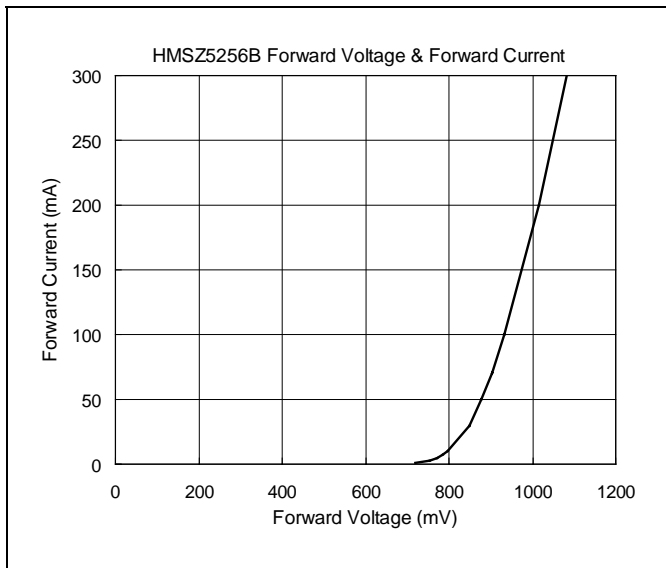
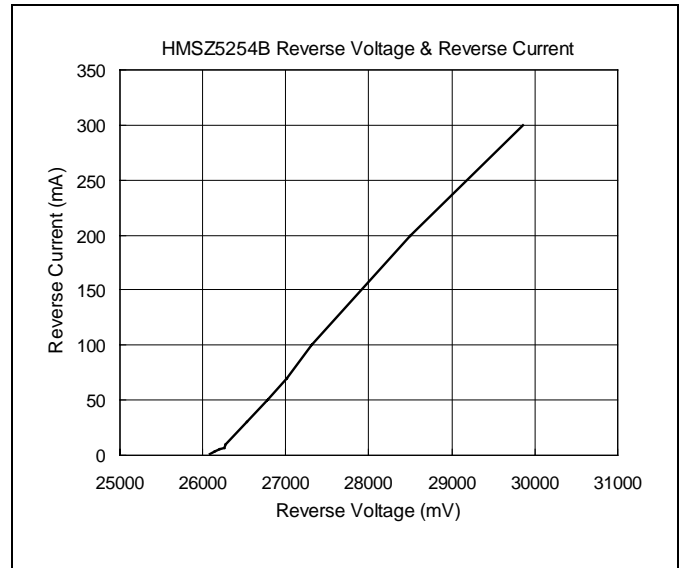
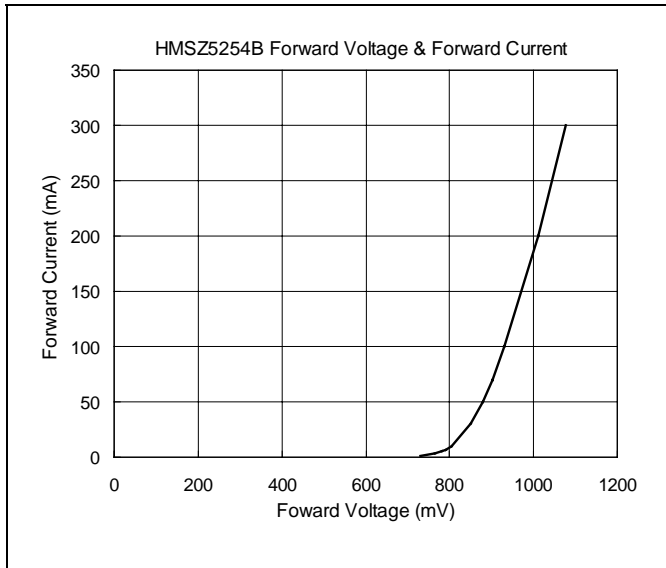














SOD-323 Dimension

Marking:

Series Code
(Refer to Page1)

Pb Free Mark
 Pb-Free: "●" (Note)
 Normal: None

Note: Pb-free product can distinguish by the green label or the extra description on the right side of the label.

Pin Style: 1.Cathode 2.Anode

Material:

- Lead solder plating: Sn60/Pb40 (Normal), Sn/3.0Ag/0.5Cu or Pure-Tin (Pb-free)
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

DIM	Min.	Max.
A	1.60	1.80
B	1.15	1.35
C	0.80	1.00
D	0.25	0.40
E	0.15	-
H	0.00	0.10
J	0.089	0.177
K	2.30	2.70

*: Typical, Unit: mm

2-Lead SOD-323 Plastic
 Surface Mounted Package
 HSMC Package Code: SL

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- **HSMC semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
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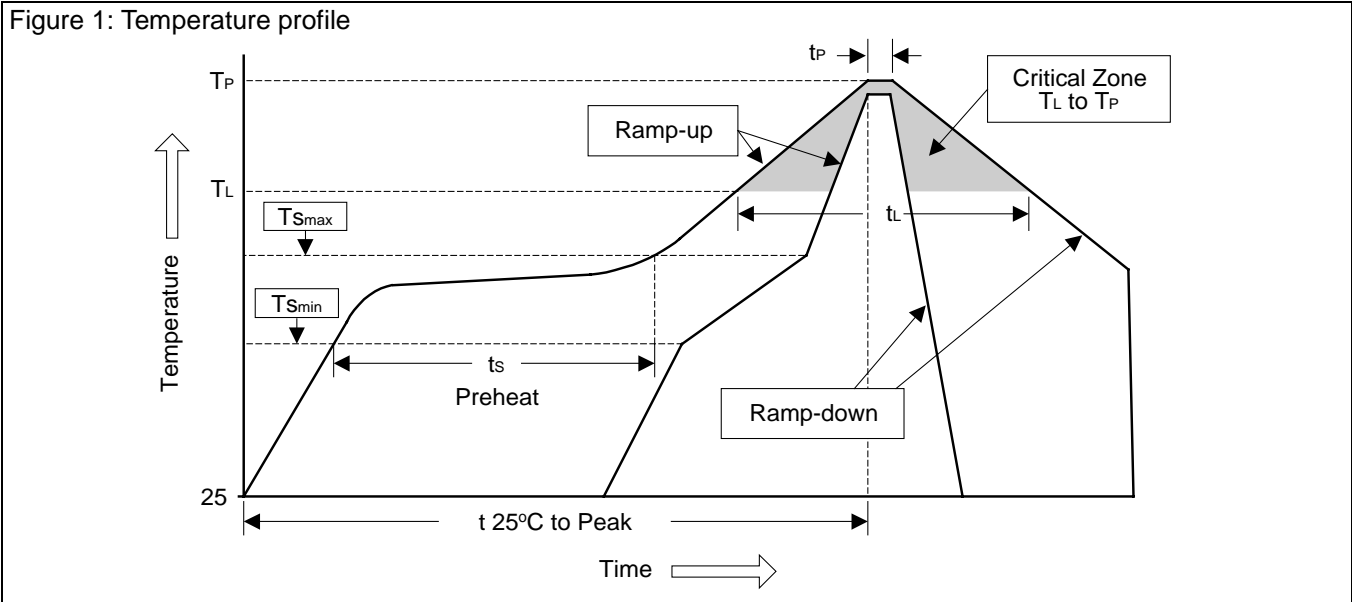
Head Office And Factory:

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F., No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.
 Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C
 Tel: 886-3-5983621~5 Fax: 886-3-5982931



Soldering Methods for HSMC's Products

1. Storage environment: Temperature=10°C~35°C Humidity=65%±15%
2. Reflow soldering of surface-mount devices



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$	$<3^{\circ}\text{C}/\text{sec}$
Preheat		
- Temperature Min (T_{Smin})	100°C	150°C
- Temperature Max (T_{Smax})	150°C	200°C
- Time (min to max) (t_s)	60~120 sec	60~180 sec
T_{Smax} to T_L		
- Ramp-up Rate	$<3^{\circ}\text{C}/\text{sec}$	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above:		
- Temperature (T_L)	183°C	217°C
- Time (t_L)	60~150 sec	60~150 sec
Peak Temperature (T_P)	240°C +0/-5°C	260°C +0/-5°C
Time within 5°C of actual Peak Temperature (t_p)	10~30 sec	20~40 sec
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	<6 minutes	<8 minutes

3. Flow (wave) soldering (solder dipping)

Products	Peak temperature	Dipping time
Pb devices.	245°C ±5°C	5sec ±1sec
Pb-Free devices.	260°C +0/-5°C	5sec ±1sec